Title (en)

METHOD FOR PRODUCING CERAMIC CIRCUIT BOARDS FROM CERAMIC SUBSTRATES HAVING METAL-FILLED VIAS

Title (de)

VERFAHREN ZUM HERSTELLEN KERAMISCHER LEITERPLATTEN AUS KERAMIKSUBSTRATEN MIT METALLGEFÜLLTEN VIAS

Title (fr)

PROCÉDÉ POUR FABRIQUER DES CARTES DE CIRCUIT IMPRIMÉ CÉRAMIQUES À PARTIR DE SUBSTRATS CÉRAMIQUES COMPRENANT DES VIAS REMPLIS DE MÉTAL

Publication

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Application

EP 13721642 A 20130430

Priority

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Abstract (en)

[origin: WO2013164348A1] The invention relates to a method for producing ceramic circuit boards from ceramic substrates having metal-filled vias. In order to be able to fill the vias by means of a single filling process, either a planar copper metallization is applied on one side to the ceramic substrate having vias by means of screen printing, or a copper film of 100 - 300 mum is bonded on one side to the ceramic substrate having vias in a DCB/DBC process and the vias are filled from the ceramic side by means of an electrogalvanic process in a copper bath by the deposition of copper.

IPC 8 full level

H05K 1/03 (2006.01); **H05K 3/10** (2006.01)

CPC (source: CN EP US)

H05K 1/0306 (2013.01 - CN EP US); **H05K 1/115** (2013.01 - US); **H05K 3/027** (2013.01 - US); **H05K 3/241** (2013.01 - US); **H05K 3/425** (2013.01 - CN EP US); H05K 3/043 (2013.01 - EP US); H05K 3/108 (2013.01 - CN EP US); H05K 2201/09563 (2013.01 - CN EP US); H05K 2203/0723 (2013.01 - CN EP US); H05K 2203/0733 (2013.01 - CN EP US)

Citation (search report)

See references of WO 2013164348A1

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